GOLD ETCHING SOP

October 2013

Purpose:

To remove the areas of gold unprotected by photoresist and thereby form the desired metallization pattern.

Precautions:

1. This operation should be started within 30 minutes of the completion of hard bake.

2. Mix 4g KI, 1g I2, 40 ml H2O or some equal ratio. The etch rate of the Au is 0.5-1 microns/minute.

Procedure:

1. Pour gold etch Solution into the Pyrex beaker marked for this purpose.

2. Agitate the wafer in the solution, keeping watch over the gold etching process.

3. Rinse the wafer with DI water using QDR.

4. Dry the wafer in SRD.

5. Inspect the wafers under the high power optical microscope.

6. If wafer appears unetched or exposed Au is left on the wafer surface repeat steps 2 to 6 till Au appears etched. Each additional etching step should be no longer than 30 seconds.